Plaskon AMC-2RC

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy molding compound specifically formulated for encapsulation of stress sensitive electronic devices including DIPs, SOICs, SSOPs and PLCCs. It can be used in conventional or automold applications.

General Information			
Features	Semi-conductive Low viscosity Fast curing		
Uses	Electrical/Electronic Applications Application in Automobile Field		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.91	g/cm³	ASTM D792
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus	1.66	MPa	ASTM D790
Flexural Strength	0.0132	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	147	°C	ASTM E1356
CLTE - Flow	1.4E-5	cm/cm/°C	ASTM D696
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	1.0E+16	ohms·cm	ASTM D257
Dielectric Strength (1.50 mm)	31	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.55		ASTM D150
Dissipation Factor (1 kHz)	2.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	32	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: 5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 3 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 175°C, 1000 psi: 76 cmAutomatic Orifice Viscosity, 175°C, Shear Rate is 100000 sec-1, 1 mm die length, 1/2 mm diameter: 70 poiseRam Follower Gel Time, 175°C: 10 secAsh Content: 79 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D, 75 sec, 175°C: 72All test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 14 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 60 cm^-6/cm/°C
The following information was transfer molded and post cured for 6 hours at 175°C
Glass Transition Temperature Tg: 155°C
Linear Thermal Expansion, Alpha 1: 12 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 61 cm^-6/cm/°C

Injection instructions

Conventional Resin TransferMolding:
Preheat Temperature: 85 to 95°C
Molding Temperature: 175°C
Molding Pressure: 56 to 98 kg/mm^2
Cycle Time: <90 sec
Post Mold Cure Time, 175°C: 0 to 2 hr
Transfer Time: 8 to 15sec
Auto Resin TransferMolding:
Transfer Time6 to 12 hr
Cycle Time:30 to 60 sec
Post Mold Cure Time, 175°C: 0 to 2 hr

Recommended distributors for this material

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